

IN THE CLAIMS:

Claims 1-18 have been amended. All of the pending claims 1 through 18 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Currently Amended) A method for fabricating at least one emission structure, comprising:
forming at least one conductive structure extending across at least a portion of a substrate; substantially removing a longitudinal portion of said the at least one conductive structure to define at least one conductive layer substantially perpendicular to said the substrate, said the substrate being exposed along a length of said the at least one conductive layer; and forming at least one emission structure adjacent said the at least one conductive layer.
2. (Currently Amended) The method of claim 1, wherein said forming said the at least one emission structure includes forming an emitter tip.
3. (Currently Amended) The method of claim 2, wherein said forming said the at least one emission structure further includes forming a resistor corresponding to said the at least one emitter tip.
4. (Currently Amended) The method of claim 3, wherein said forming said the resistor comprises forming said the resistor adjacent to said the at least one conductive layer.
5. (Currently Amended) The method of claim 1, wherein said forming said the at least one emission structure comprises forming a plurality of lines of emission structures.
6. (Currently Amended) The method of claim 5, wherein said substantially removing comprises electrically isolating at least one emission structure located along a first line

of said the plurality of lines from at least one emission structure located along an adjacent, second line of said the plurality of lines.

7. (Currently Amended) The method of claim 1, wherein said forming said the at least one conductive structure comprises:

disposing a layer comprising conductive material over said the substrate; and patterning said the layer.

8. (Currently Amended) The method of claim 1, wherein said forming said the at least one emission structure comprises forming said the at least one emission structure from at least one of semiconductive material and conductive material.

9. (Currently Amended) The method of claim 1, wherein said forming said the at least one emission structure comprises forming said the at least one emission structure so as to extend over a lateral edge of said the at least one conductive structure.

10. (Currently Amended) A method for fabricating at least one emission structure, comprising:

forming at least one conductive structure that extends at least partially across a substrate; forming at least one emitter tip and a corresponding resistor adjacent to said the at least one conductive structure; and

substantially removing at least a longitudinal portion of said the at least one conductive structure along substantially an entire length thereof to define at least one conductive layer substantially perpendicular to said the substrate.

11. (Currently Amended) The method of claim 10, wherein said forming said the at least one conductive structure comprises:

disposing a layer comprising conductive material on ~~said~~ the substrate; and patterning ~~said~~ the layer.

12. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one emitter tip comprises forming ~~said~~ the at least one emitter tip from at least one of semiconductive material and conductive material.

13. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the corresponding resistor comprises forming ~~said~~ the corresponding resistor from at least one of semiconductive material and conductive material.

14. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one emitter tip comprises:
disposing at least one layer comprising at least one of semiconductive material and conductive material over ~~said~~ the substrate and ~~said~~ the at least one conductive structure;
removing a longitudinal portion of at least one region of ~~said~~ the at least one layer located over ~~said~~ the at least one conductive structure to expose at least a substantially longitudinal portion of ~~said~~ the at least one conductive structure; and patterning at least one remaining portion of ~~said~~ the at least one layer.

15. (Currently Amended) The method of claim 14, wherein ~~said~~ patterning ~~said~~ the at least one remaining portion of ~~said~~ the at least one layer includes defining ~~said~~ the at least one emitter tip from ~~said~~ the at least one layer.

16. (Currently Amended) The method of claim 15, wherein ~~said~~ patterning ~~said~~ the at least one remaining portion of ~~said~~ the at least one layer further includes forming ~~said~~ the corresponding resistor.

17. (Currently Amended) The method of claim 10, wherein ~~said~~-substantially removing comprises leaving at least a lateral edge of ~~said~~ the at least one conductive structure along substantially ~~said~~ the entire length thereof.

18. (Currently Amended) The method of claim 10, wherein ~~said~~-forming ~~said~~ the at least one emitter tip comprises forming ~~said~~ the at least one emitter tip so as to extend over a lateral edge of ~~said~~ the at least one conductive structure.